



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



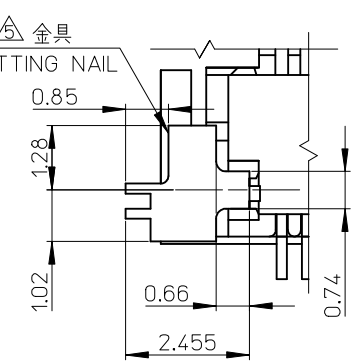
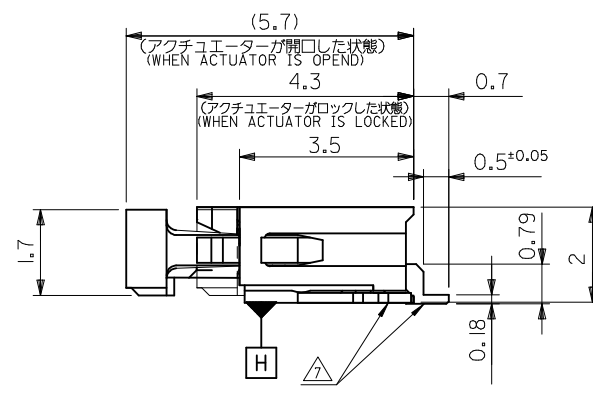
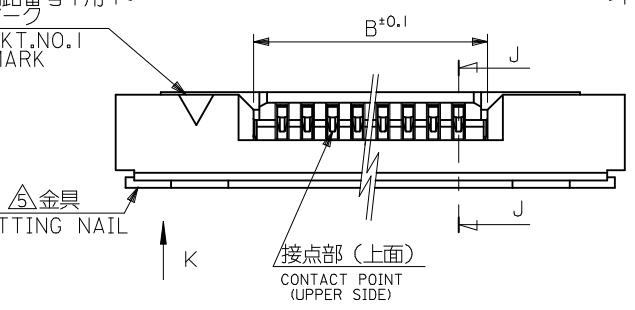
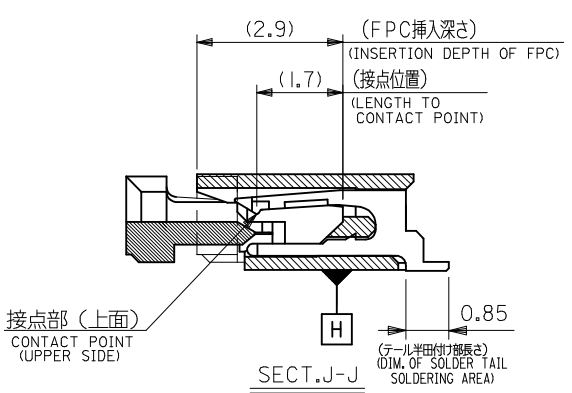
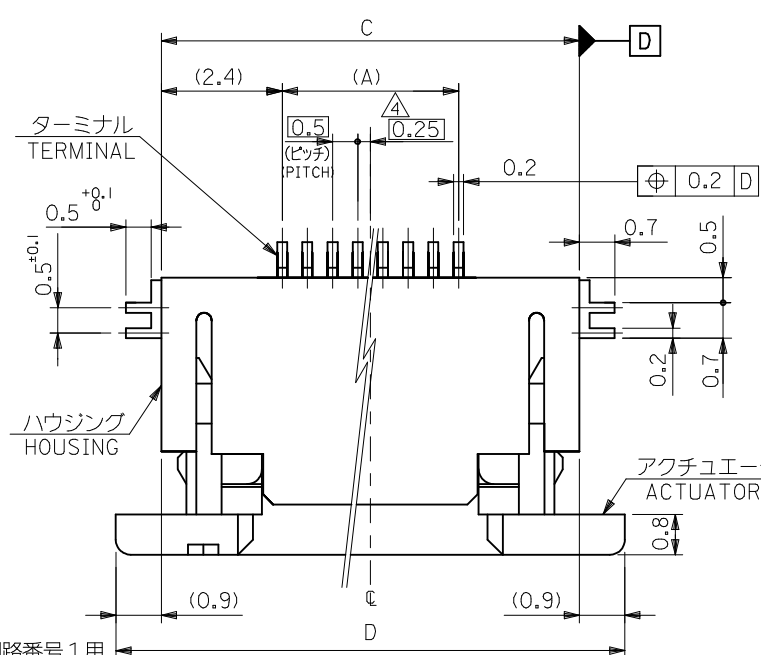
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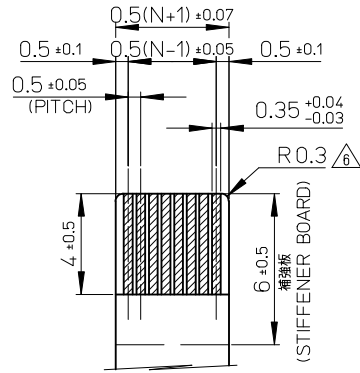


注記NOTES
 1.使用材料 MATERIAL
 ハウジング:ポリアミド(R/PA), ガラス充填, UL94V-0, ナチュラル(白)
 HOUSING:POLYAMIDE, GLASS FILLED, UL94V-0, NATURAL (WHITE)
 アクチュエータ:ポリフェニレンスルフィド (PPS), ガラス充填, UL94V-0, 黒
 ACTUATOR:POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル:リン青銅, (t=0.2)
 TERMINAL:PHOSPHOR BRONZE
 金具:リン青銅, (t=0.2)
 FITTING NAIL:PHOSPHOR BRONZE
 2.めっき仕様 PLATING
 ターミナル TERMINAL
 鍍銀ピスマスめっき(1.0μm以上)
 下地:ニッケルめっき(1.0μm以上)
 TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATE:NICKEL PLATING (1.0 MICROMETER MINIMUM)
 金具: FITTING NAIL
 鍍めっき(1.0μm以上)
 下地:ニッケルめっき(1.0μm以上)
 TIN PLATING (1.0 MICROMETER MINIMUM)
 UNDER PLATE:NICKEL PLATING (1.0 MICROMETER MINIMUM)
 3.エンボスステップ組立時は、アクチュエータがロックした状態になります。
 IN THE PACKAGE, ACTUATOR SHOULD BE LOCKED.
 4. 複数極に適用 APPLY FOR EVEN CIRCUIT.
 パッケージ裏面に適用
 5. FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.
 RO:3は、FPCの隣接部にかからないこと
 6. RO:3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.
 シルダータール方向のズレ量、及び金具半田付け面のずれ量は、基準面 ④ に対し上方向0.1 MAX., 下方向0.15MAXとする。
 7. MISALIGNMENT OF SOLDER TAIL S AND FITTING NAILS FROM ④ UPPER DIRECTION 0.1 MAX., LOWER DIRECTION 0.15 MAX.
 8. ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT.

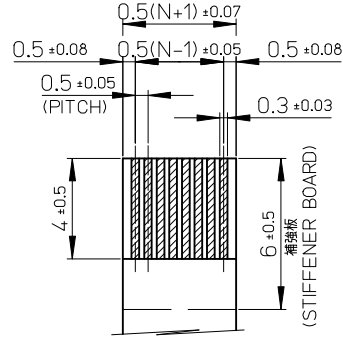
16.1	14.3	10.65	9.5	52745-2033	20
15.6	13.8	10.15	9	52745-1933	19
15.1	13.3	9.65	8.5	52745-1833	18
14.6	12.8	9.15	8	52745-1733	17
14.1	12.3	8.65	7.5	52745-1633	16
13.6	11.8	8.15	7	52745-1533	15
13.1	11.3	7.65	6.5	52745-1433	14
12.6	10.8	7.15	6	52745-1333	13
12.1	10.3	6.65	5.5	52745-1233	12
11.6	9.8	6.15	5	52745-1133	11
11.1	9.3	5.65	4.5	52745-1033	10
10.6	8.8	5.15	4	52745-0933	9
10.1	8.3	4.65	3.5	52745-0833	8
9.6	7.8	4.15	3	52745-0733	7
9.1	7.3	3.65	2.5	52745-0633	6
8.1	6.3	2.65	1.5	52745-0433	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**22

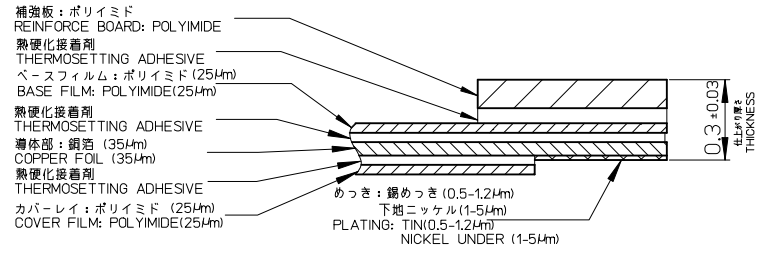
REVISED EC NO: J2013-1168 DRWN:NASUNUMA 2013/04/15 CHKD:KAKAHASHI 2013/04/15 APPR:KMORIKAWA 2013/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	10:1	METRIC	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	±0.25	TMORISHITA	2012/09/06	0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)	
30 OVER	±0.3	CHECKED BY	DATE			
		APPROVED BY	DATE			
		ANGULAR	±3 °			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
		MATERIAL NO.		DOCUMENT NO.		SHEET NO.
		SEE CHART		SD-52745-055		1 OF 2
		SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



適合FPC推奨寸法
 APPLICABLE FPC
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



適合FFC推奨寸法
 APPLICABLE FFC
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03

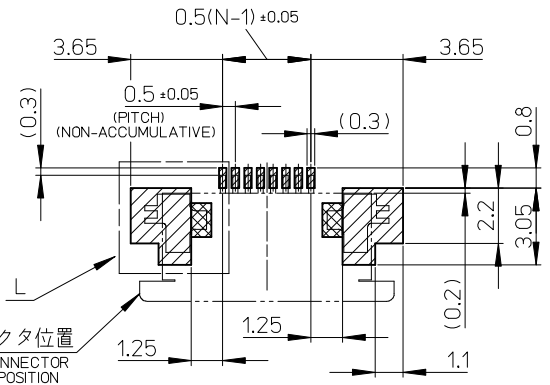
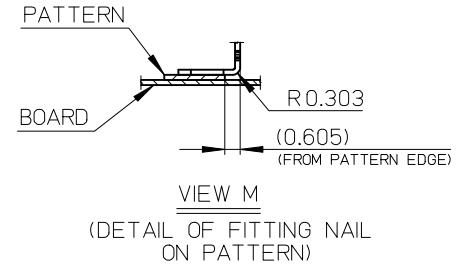
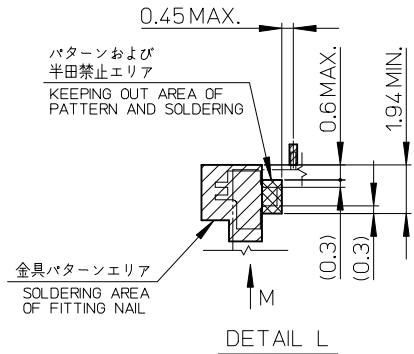


FPC構成推奨仕様
 STRUCTURE OF FPC

FPCについて:
 抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様お願い致します。

ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED MATERIAL : STIFFENER FILM POLYIMIDE
 BONDING AGENT : THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
 BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
 CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

FFC/FPCについて:
 打抜き方向は導体側から補強板側を推奨致します。
 導体部については軟銅箔35μmまたは50μmを推奨致します。
 ABOUT FFC/FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPECIFICATION:
 THICKNESS OF SOFT COPPER FOIL: 35MICROMETER
 OR 50 MICROMETER



推奨基板レイアウト
 (マウント面)
 RECOMMENDED P.C BOARD
 PATTERN DIMENSION
 (MOUNTING SIDE)
 マスク厚 : 100 μm
 マスク開口率 : 100%
 SCREEN THICKNESS : 100 μm
 SCREEN OPEN TATIO : 100%

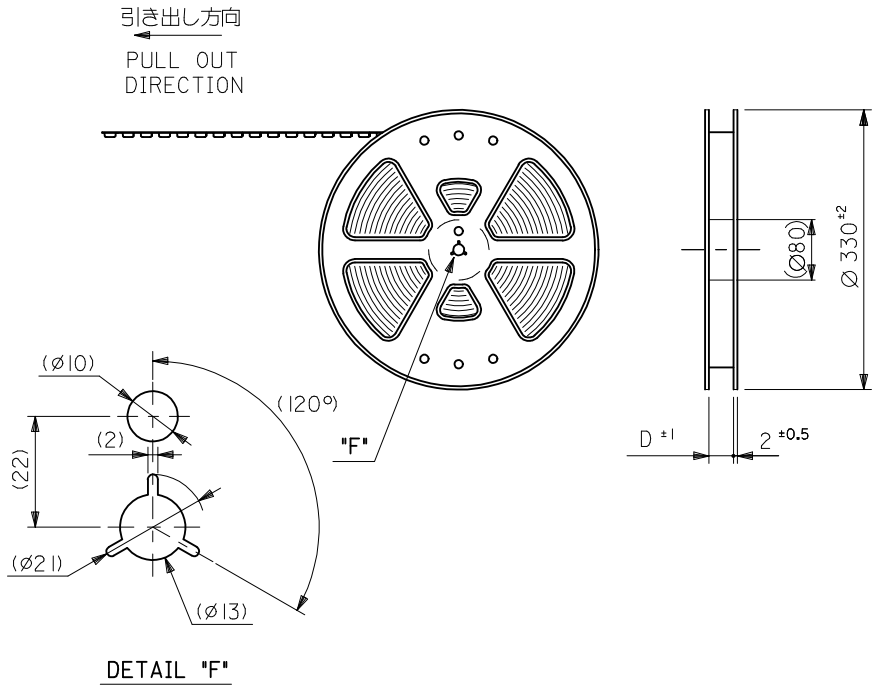
REVISED EC NO: J2013-1168 DRWN:KONDO 2013/03/15 CHKD:KAKAHASHI 2013/03/15 APPR:KMORIKAWA 2013/04/25	DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/06	TITLE 0.5MM FPC CONN ZIF R/A HOUSING ASSY (UPPER CONTACT)		
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2013/04/15	molex DOCUMENT NO. SD-52745-055 SHEET NO. 2 OF 2		
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15			
ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. ENTER PART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

- 製品番号 52745-***22の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面SD-52745-055を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-***22 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-055
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープ リーダー部 175 ±25	トップテープ 未接着部 25 ±5
TOP TAPE LEADER PART	TOP TAPE NON-BONDED PART

引き出し方向 PULL OUT DIRECTION	リーダー部 (空部) LEADER PART (EMPTY) 120 ±20	部品挿入部 COMPONENT SUPPLIER	末端部 (空部) TAIL PART (EMPTY) 150 ±40
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- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

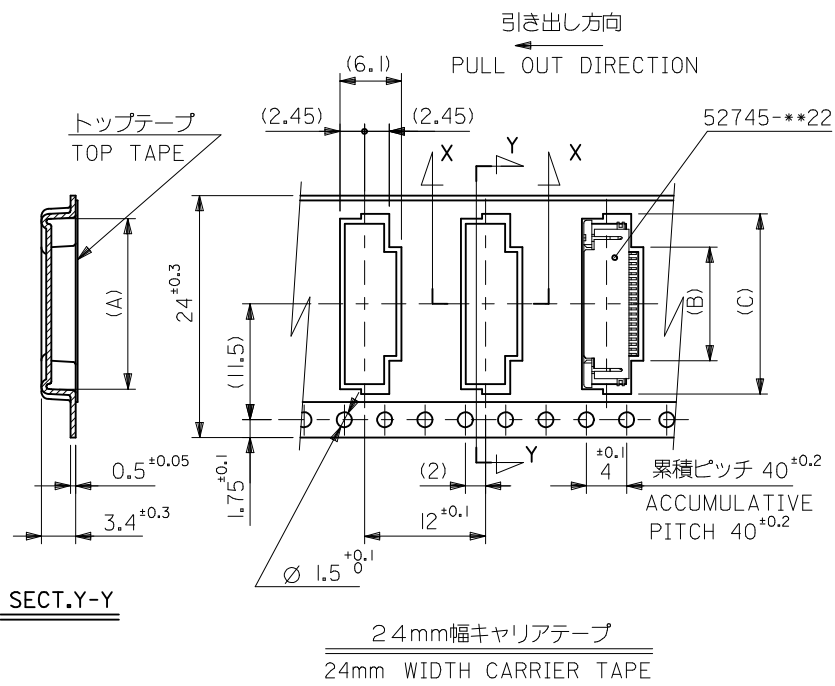


5. 材料
 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS) <リサイクル材を含む>

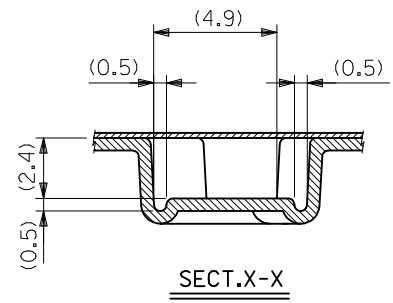
MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYREN(PS)
 <RECYCLE MATERIAL CONTAINED>

6. ELV及RoHS適合品
 ELV AND RoHS COMPLIANT

RELEASED EC NO.: J2013-1014 DRWN:TMORISHITA 2012/09/05 CHKD:KTAKAHASHI 2012/09/07 APPR:KMORIKAWA 2013/03/15	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07					
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15	DOCUMENT NO. SD-52745-056 SHEET NO. 1 OF 3				
		ANGULAR ±3 °		MATERIAL NO.						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



SECT.Y-Y



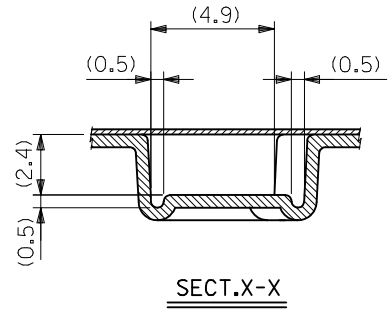
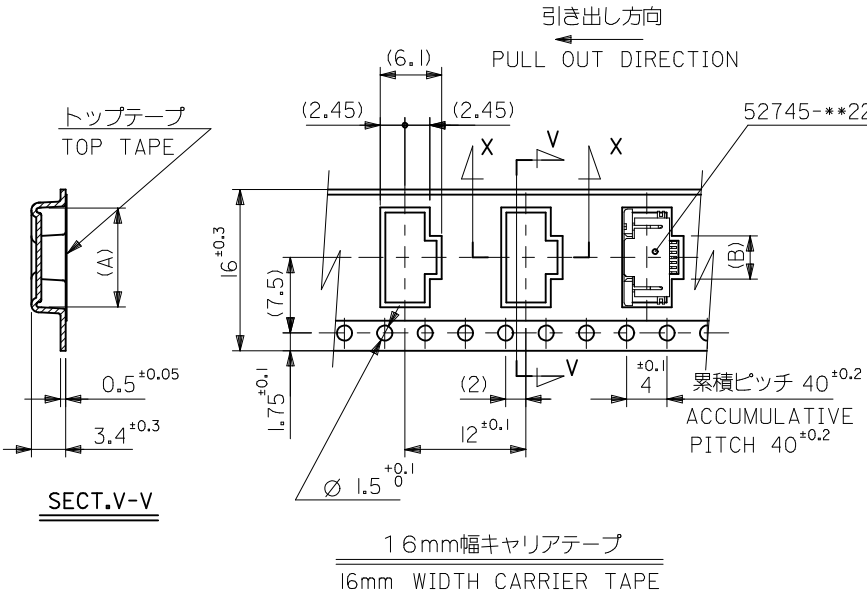
SECT.X-X

24	25.5	17.4	10.8	16.4	52745-2033	20
		16.9	10.3	15.9	-1933	19
		16.4	9.8	15.4	-1833	18
		15.9	9.3	14.9	-1733	17
		15.4	8.8	14.4	-1633	16
		14.9	8.3	13.9	-1533	15
		14.4	7.8	13.4	-1433	14
		13.9	7.3	12.9	-1333	13
		13.4	6.8	12.4	-1233	12
		12.9	6.3	11.9	-1133	11
		12.4	5.8	11.4	-1033	10
		11.9	5.3	10.9	-0933	9
		11.4	4.8	10.4	-0833	8
		10.9	4.3	9.9	-0733	7
10.4	3.8	9.4	52745-0633	6		

キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CIRCUIT
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CONNECTOR SERIES NO. : 52745-**-22

RELEASED EC NO. J2013-1014 DRWN: TMORISHITA 2012/09/05 CHKD: KTAKAHASHI 2012/09/07 APPR: KMORIKAWA 2013/03/15 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY TMORISHITA	DATE 2012/09/05	TITLE EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/07			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15			
	ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52745-056		2 OF 3	



SECT.V-V

SECT.X-X

16	17.5	2.8	8.4	52745-0433	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CIRCUIT

RELEASED EC NO: J2013-1014 DRWN: TMORISHITA 2012/09/05 CHKD: KTAKAHASHI 2012/09/07 APPR: KMORIKAWA 2013/03/15	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
		10 OVER 30 UNDER	±0.25	TMORISHITA	2012/09/07	EMBOSS TAPE PACKAGED FOR 0.5MM FPC CONN ZIF R/A HOUSING ASSY						
		30 OVER	±0.3	KTAKAHASHI	2012/09/07	molex						
		ANGULAR ±3 °		APPROVED BY	DATE							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52745-056		3 OF 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		SIZE	A3									